Dicing Saw - KS 7100

Manager: Sam Wright  
Backup: John Treichler  
Backup: Mike Skvarla

Work Phone: 254-4836  
Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

Work Phone: 254-4949

Work Phone: 254-4674

Safety
- Do not operate with open covers
- No buddy system restrictions apply

Process Restrictions

Material Restrictions
- All types of glasses and silicon
- No GaAs substrates allowed.

Parameter Restrictions
- Do not attempt to change any parameters except index, wafer size, and depth
- Check with tool manager for wafers thicker than 1 mm

Scheduling / Sign-up Restrictions
-- Minimum Tool Time: 30 minutes
- Maximum 2 hour reservation limit

Requirements (Do Every Time)
- Load your recipe as the default recipe
- Confirm which blade is mounted on the saw
- Turn down the spindle when done
- Turn off the compressed air after turning down the spindle
- Put wafer frame latch in closed position
- Log out

Prohibitions (Never Do)
- DO NOT open the cover during operation
- DO NOT attempt to change the blade unless you have been authorized to do so
- DO NOT reach into the saw

Common Problems

<table>
<thead>
<tr>
<th>Problem:</th>
<th>Root Cause:</th>
<th>Solution:</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cannot change the index</td>
<td>Software failure</td>
<td>Contact tool manager or teach the index</td>
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</tbody>
</table>

Other Comments or Cautions